

PRODUCT DATA SHEET

WS-575-SP

Flip-Chip Flux

Features

- Water-soluble
- Halogen-free (not intentionally added)
- Suitable for spray applications
- Suitable for SnPb and Pb-free applications
- Non-corrosive to underbump metallization

Introduction

Flip-Chip Flux WS-575-SP is a liquid flux specifically designed to meet process needs for direct chip attach of fine pitch flip-chips (<0.5mm). **WS-575-SP** eliminates compatibility issues with underfills by having a completely water-cleanable residue.

Properties

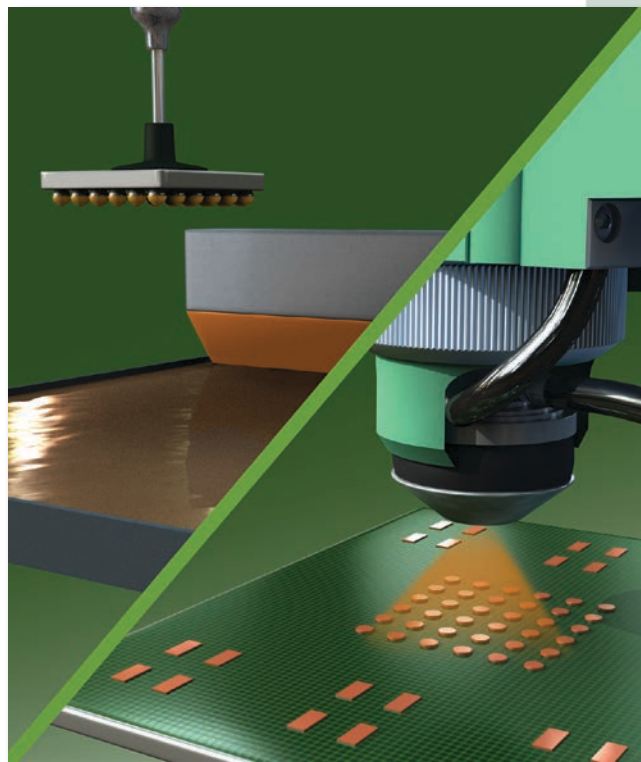
Property	Value	Test Method
Flux Type Classification:	MO	J-STD-004 (IPC-TM-650:
Typical Viscosity:	45cSt	Cannon-Fenske
SIR (Ohms, post cleaning):	Pass (>10 ⁸ after 7 days @ 85°C & 85% RH)	IPC-B-24
Typical Acid Value:	55mg KOH/g	Titration
Color:	Amber to Brown	Visual
Shelf Life:	1 year	0°C to +30°C

All information is for reference only. Not to be used as incoming product specifications.

Application

Recommended flux amount: 500-1500micrograms/mm², depending on flip-chip.

For spray applications, the flux storage tank should hold enough flux for one 8-hour shift. Additional flux remaining in tank may expire (pot life <10 hours at room temperature) if left for a prolonged amount of time. Spray equipment should also be cleaned frequently to ensure uniform spray deposition and flux purity.



Cleaning

The material can be cleaned with DI water, or water with an added cleaner. Ideal conditions for spray-cleaning: 25°C (room temperature) or higher for >1 minute at >60psi.

Packaging

WS-575-SP is available in 100g to 1 gallon (3.8 liter) containers. Other packaging can be provided to meet specific requirements.

OVER→

Form No. 98680 (A4) R2

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Flip-Chip Flux WS-575-SP

Storage

Storage temperatures should not exceed 25°C for more than 4 days, and should never exceed 30°C. Colder storage (as low as -25°C) can be used to maximize the shelf life. After removing from cold storage, **WS-575-SP** should be allowed to stand for at least 4 hours at room temperature before using.

Technical Support

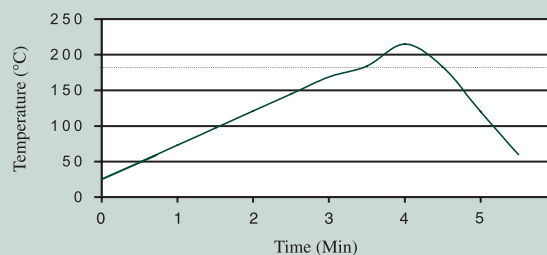
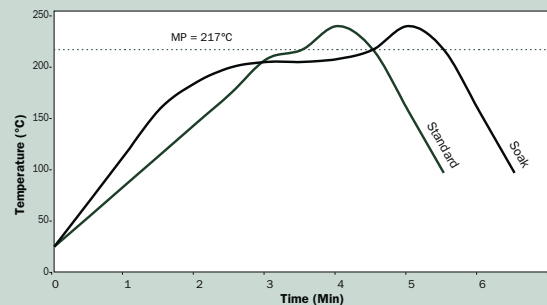
Indium Corporation sets the industry standard in providing rapid response, on-site technical support for our customers worldwide. Indium Corporation's team of Technical Support Engineers can provide expertise in all aspects of Materials Science and Semiconductor Packaging process applications.

Safety Data Sheets

The SDS for this product can be found online at <http://www.indium.com/sds>

Reflow

Recommended Profile:



Peak reflow temperature should be <340°C in an air or nitrogen atmosphere (<100ppm O₂), with a linear ramp up to 30°C above liquidus temperature. These profiles are recommended to the user as starting points, and should be optimized by the user to meet their individual process needs.

This product data sheet is provided for general information only. It is not intended, and shall not be construed, to warrant or guarantee the performance of the products described which are sold subject exclusively to written warranties and limitations thereon included in product packaging and invoices. All Indium Corporation's products and solutions are designed to be commercially available unless specifically stated otherwise.

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